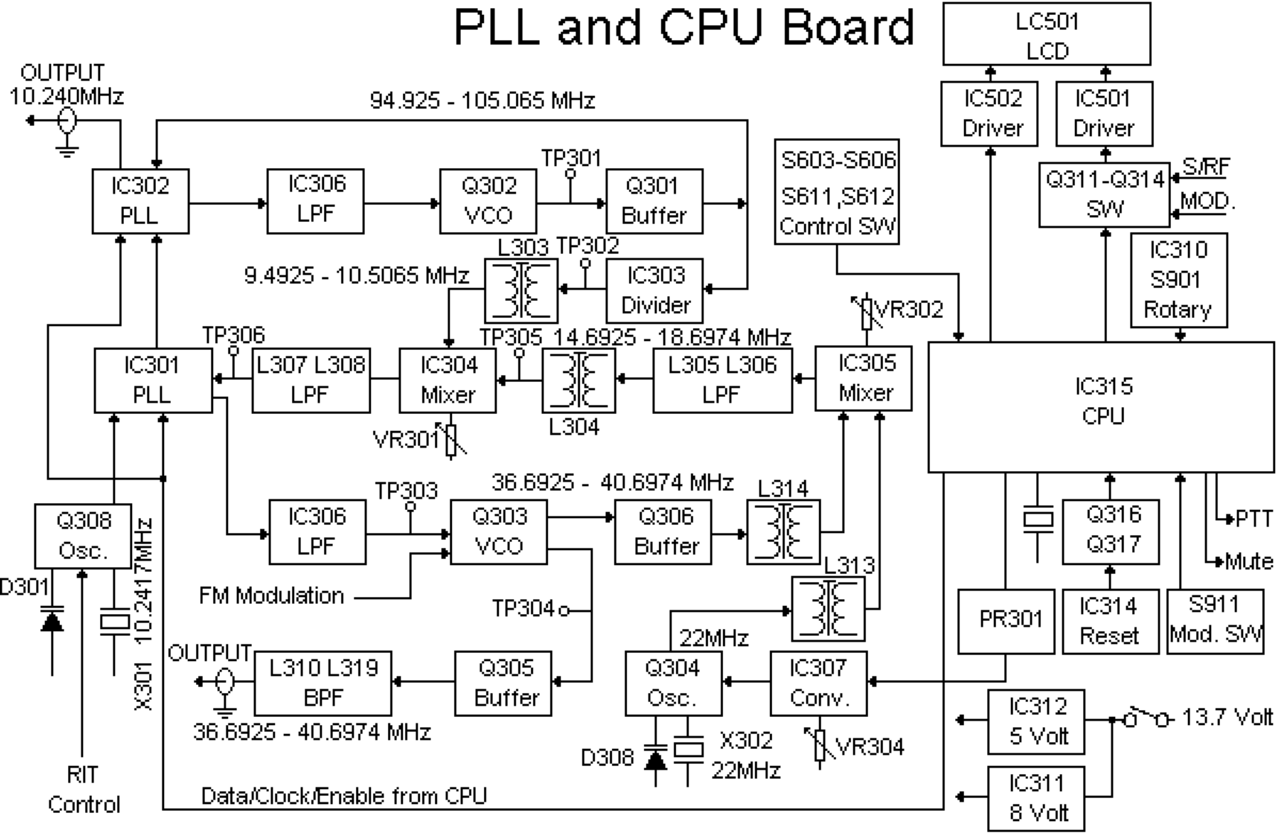
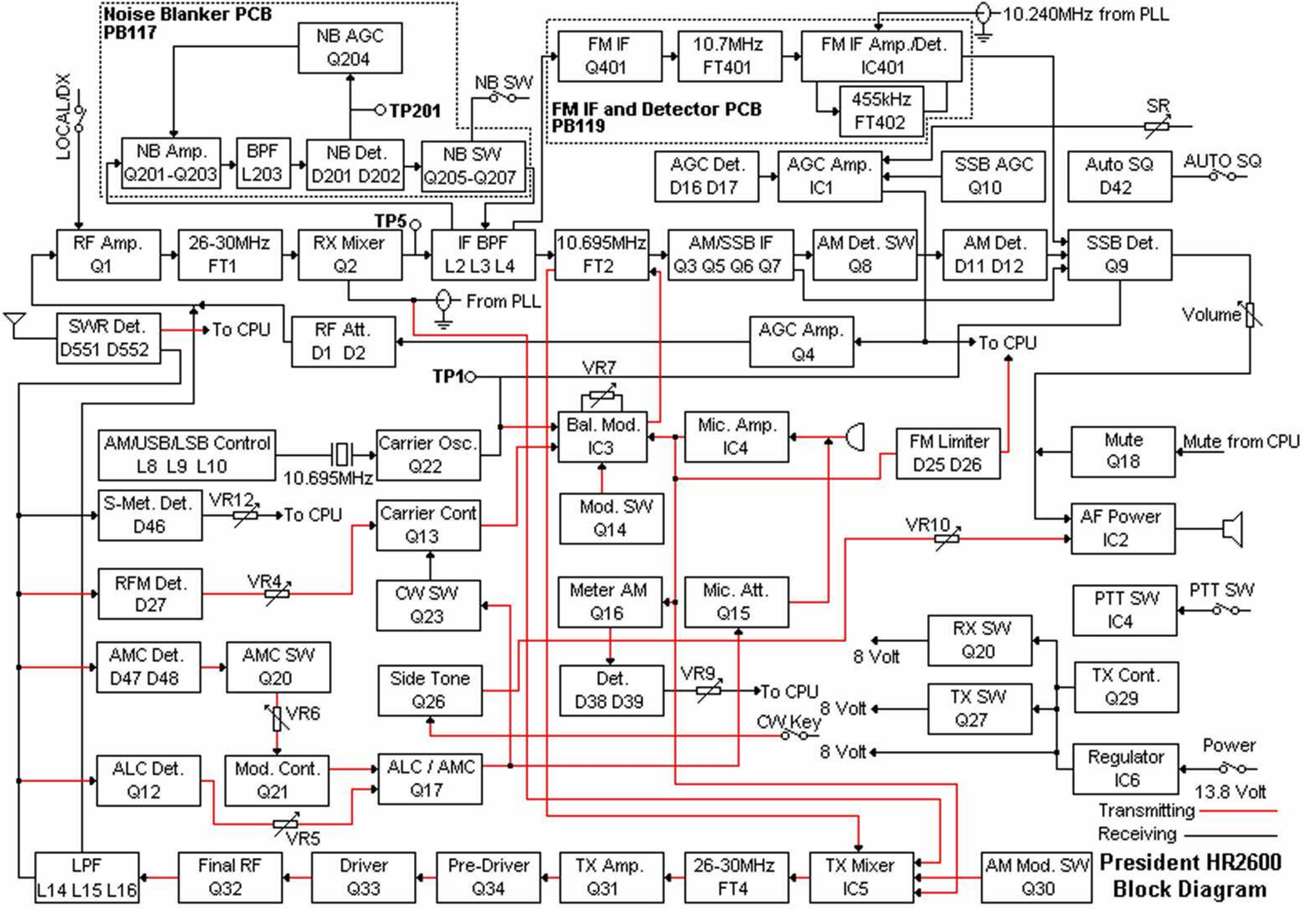
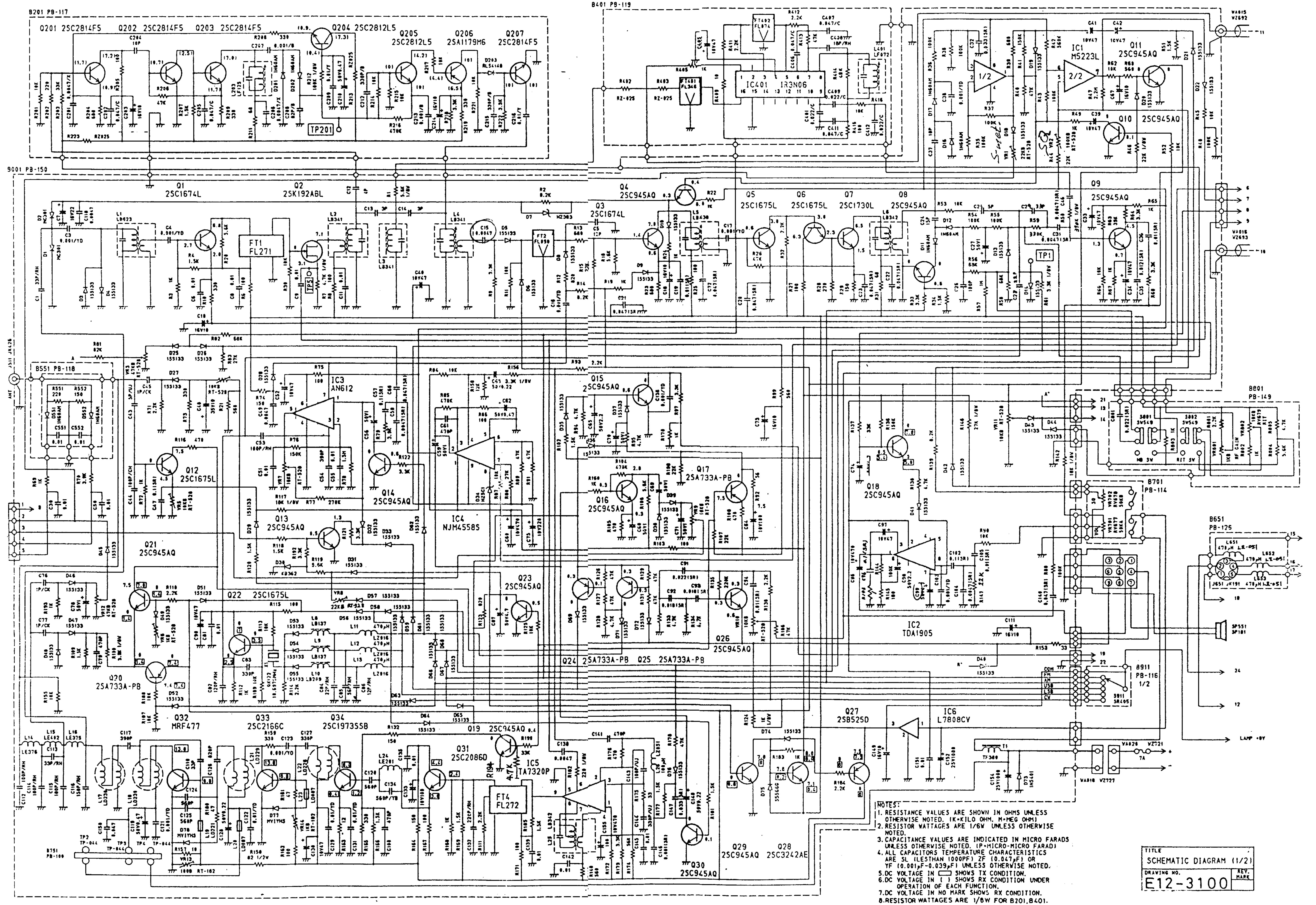
PLL and CPU Board





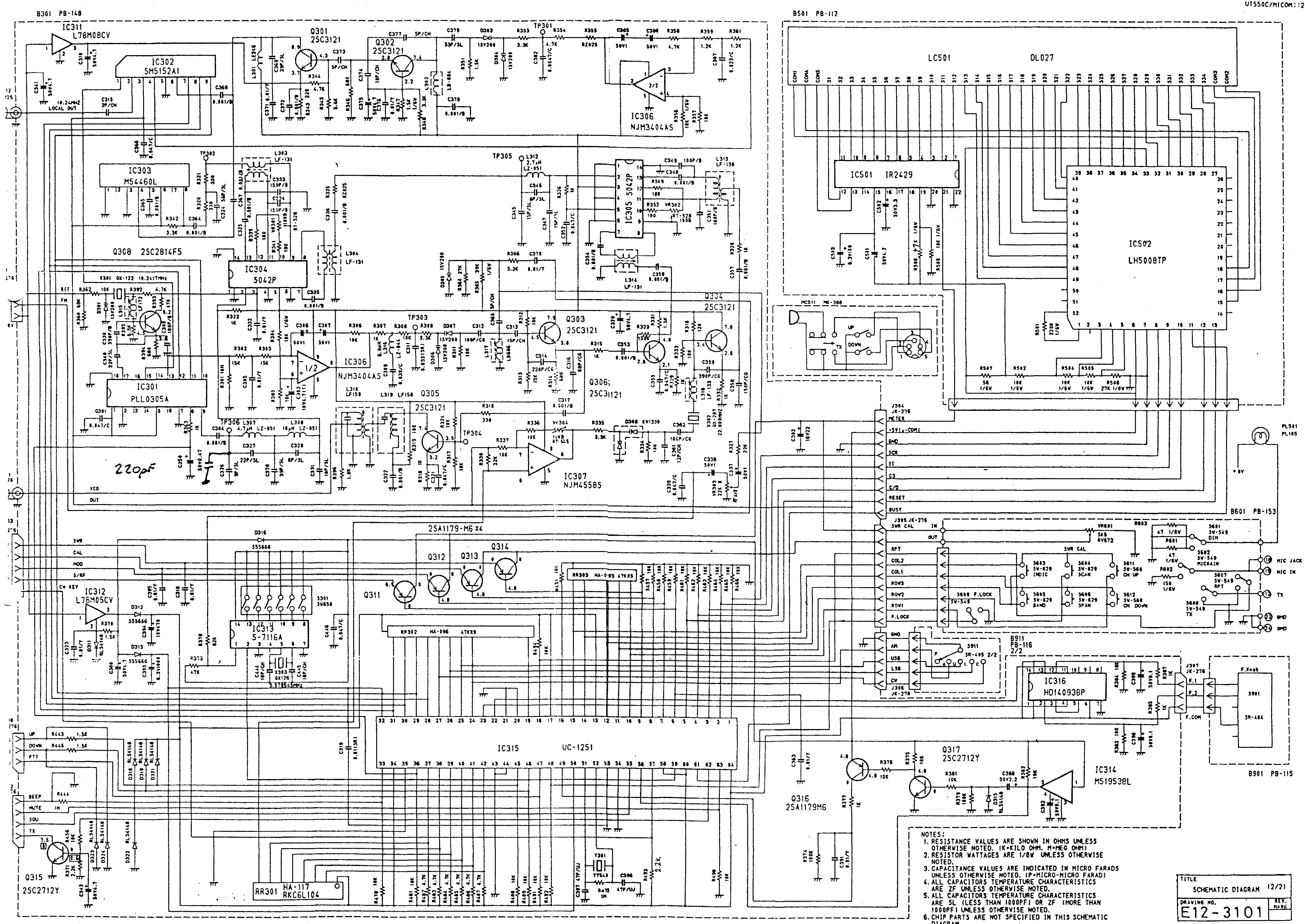
President HR2600 Block Diagram



NOTES:

1. RESISTANCE VALUES ARE SHOWN IN OHMS UNLESS OTHERWISE NOTED. (K=KILO OHM, M=MEG OHM)
2. RESISTOR WATTAGES ARE 1/6W UNLESS OTHERWISE NOTED.
3. CAPACITANCE VALUES ARE INDICATED IN MICRO FARADS UNLESS OTHERWISE NOTED. (P=MICRO-MICRO FARAD)
4. ALL CAPACITORS TEMPERATURE CHARACTERISTICS ARE SL (LESTHAN 1000PF) ZF (0.047μF) OR YF (0.001μF-0.039μF) UNLESS OTHERWISE NOTED.
5. DC VOLTAGE IN ▭ SHOWS TX CONDITION.
6. DC VOLTAGE IN ( ) SHOWS RX CONDITION UNDER OPERATION OF EACH FUNCTION.
7. DC VOLTAGE IN NO MARK SHOWS RX CONDITION.
8. RESISTOR WATTAGES ARE 1/8W FOR B201, B401.

TITLE	
SCHEMATIC DIAGRAM (1/2)	
DRAWING NO. E12-3100	REV. MARK



NOTES:
1. RESISTANCE VALUES ARE SHOWN IN OHMS UNLESS OTHERWISE NOTED. (K=KILO OHM. M=MEG OHM)
2. RESISTOR WATTAGES ARE 1/8W UNLESS OTHERWISE NOTED.
3. CAPACITANCE VALUES ARE INDICATED IN MICRO FARADS UNLESS OTHERWISE NOTED. (P=MICRO-MICRO FARAD)
4. ALL CAPACITORS TEMPERATURE CHARACTERISTICS ARE ZF UNLESS OTHERWISE NOTED.
5. ALL CAPACITORS TEMPERATURE CHARACTERISTICS ARE SL (LESS THAN 1000PF) OR ZF (MORE THAN 1000PF) UNLESS OTHERWISE NOTED.
6. CHIP PARTS ARE NOT SPECIFIED IN THIS SCHEMATIC DIAGRAM.
PLEASE REFER TO THE PARTS LIST FOR THE CHIP PARTS.

TITLE	
SCHEMATIC DIAGRAM (2/2)	
DRAWING NO.	REV. MARK
E12-3101	